

| | Hits | Search Text | DBs |
|----|------|--|---|
| 22 | 8 | MEMS and LATENT ADJ MASK\$3 | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB |
| 23 | 1 | MEMS and LATENT near MASK\$3 not (MEMS and LATENT ADJ MASK\$3) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB |
| 24 | 11 | MEMS and LATENT WITH MASK\$3 not ((MEMS and LATENT ADJ MASK\$3) (MEMS and LATENT near MASK\$3 not (MEMS and LATENT ADJ MASK\$3))) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB |
| 25 | 5 | MEMS and LATENT SAME MASK\$3 not ((MEMS and LATENT ADJ MASK\$3) (MEMS and LATENT near MASK\$3 not (MEMS and LATENT ADJ MASK\$3))) (MEMS and LATENT WITH MASK\$3 not ((MEMS and LATENT ADJ MASK\$3) (MEMS and LATENT near MASK\$3 not (MEMS and LATENT ADJ MASK\$3)))) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB |
| 26 | 308 | MEMS and LATENT AND MASK\$3 not ((MEMS and LATENT ADJ MASK\$3) (MEMS and LATENT near MASK\$3 not (MEMS and LATENT ADJ MASK\$3))) (MEMS and LATENT WITH MASK\$3 not ((MEMS and LATENT ADJ MASK\$3) (MEMS and LATENT near MASK\$3 not (MEMS and LATENT ADJ MASK\$3)))) (MEMS and LATENT SAME MASK\$3 not ((MEMS and LATENT ADJ MASK\$3) (MEMS and LATENT near MASK\$3 not (MEMS and LATENT ADJ MASK\$3))) (MEMS and LATENT WITH MASK\$3 not ((MEMS and LATENT ADJ MASK\$3) (MEMS and LATENT near MASK\$3 not (MEMS and LATENT ADJ MASK\$3)))) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB |
| 27 | 131 | MEMS SAME LATENT AND MASK\$3 not ((MEMS and LATENT ADJ MASK\$3) (MEMS and LATENT near MASK\$3 not (MEMS and LATENT ADJ MASK\$3))) (MEMS and LATENT WITH MASK\$3 not ((MEMS and LATENT ADJ MASK\$3) (MEMS and LATENT near MASK\$3 not (MEMS and LATENT ADJ MASK\$3)))) (MEMS and LATENT SAME MASK\$3 not ((MEMS and LATENT ADJ MASK\$3) (MEMS and LATENT near MASK\$3 not (MEMS and LATENT ADJ MASK\$3))) (MEMS and LATENT WITH MASK\$3 not ((MEMS and LATENT ADJ MASK\$3) (MEMS and LATENT near MASK\$3 not (MEMS and LATENT ADJ MASK\$3)))) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB |
| 28 | 0 | MEMS WITH LATENT AND MASK\$3 not ((MEMS and LATENT ADJ MASK\$3) (MEMS and LATENT near MASK\$3 not (MEMS and LATENT ADJ MASK\$3))) (MEMS and LATENT WITH MASK\$3 not ((MEMS and LATENT ADJ MASK\$3) (MEMS and LATENT near MASK\$3 not (MEMS and LATENT ADJ MASK\$3)))) (MEMS and LATENT SAME MASK\$3 not ((MEMS and LATENT ADJ MASK\$3) (MEMS and LATENT near MASK\$3 not (MEMS and LATENT ADJ MASK\$3))) (MEMS and LATENT WITH MASK\$3 not ((MEMS and LATENT ADJ MASK\$3) (MEMS and LATENT near MASK\$3 not (MEMS and LATENT ADJ MASK\$3)))) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB |
| 29 | 109 | mems AND GATE ADJ OXIDE | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB |
| 30 | 13 | mems and (gate adj oxide) with nitride | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB |
| 31 | 13 | mems and (gate adj oxide) same nitride not (mems and (gate adj oxide) with nitride) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB |
| 32 | 177 | lab-on-a-chip "lab-on-a-chip" "lab on a chip" | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB |
| 33 | 0 | (lab-on-a-chip "lab-on-a-chip" "lab on a chip") and locos | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB |
| 34 | 0 | (lab-on-a-chip "lab-on-a-chip" "lab on a chip") and smile | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB |
| 35 | 2 | (lab-on-a-chip "lab-on-a-chip" "lab on a chip") and latent | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB |

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|----|------|--|---|
| 1 | 8 | mems and delayed adj locos | USPAT; US-PGPUB; EPO; JPO; DERWENT; |
| 2 | 62 | mems and locos | USPAT; US-PGPUB; EPO; JPO; DERWENT; |
| 3 | 54 | (mems and locos) not (mems and delayed adj locos) | USPAT; US-PGPUB; EPO; JPO; DERWENT; |
| 4 | 8 | ((mems and locos) not (mems and delayed adj locos)) and (si3n4 "Si.sub.3 N.sub.4" nitride) and thermal\$3 adj oxid\$5 | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB |
| 5 | 2 | ("6464892").PN. | USPAT; US-PGPUB; EPO; JPO; DERWENT; |
| 6 | 15 | ("4764244" "4911783" "5006202" "5131978" "5332469" "5542558" "5628917" "5658471" "5683591" "5690841" "5717251" "5770465" "6020272" "6174820" | USPAT |
| 7 | 2 | ("6444138").PN. | USPAT; US-PGPUB; EPO; JPO; DERWENT; |
| 8 | 8 | ("4911783" "5006202" "5131978" "5717251" "5770465" "6020272" "6136243" "6174820").PN. | USPAT |
| 9 | 7 | ((("4764244" "4911783" "5006202" "5131978" "5332469" "5542558" "5628917" "5658471" "5683591" "5690841" "5717251" "5770465" "6020272" "6174820" "6136243").PN.) not ((("4911783" "5006202" "5131978" "5717251" "5770465" "6020272" "6136243" "6174820").PN.) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB |
| 10 | 8 | mems and latent adj mask\$3 | USPAT; US-PGPUB; EPO; JPO; DERWENT; |
| 11 | 3999 | (MEMS wafer substrate workpiece silicon) and oxide with (((first and second) both) adj | USPAT; US-PGPUB; EPO; JPO; DERWENT; |
| 12 | 2480 | ((MEMS wafer substrate workpiece silicon) and oxide with (((first and second) both) adj side)) and etch\$3 | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB |
| 13 | 1440 | ((MEMS wafer substrate workpiece silicon) and oxide with (((first and second) both) adj side)) and etch\$3) and (photoresist resist photomask\$3) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB |
| 14 | 1126 | (((((MEMS wafer substrate workpiece silicon) and oxide with (((first and second) both) adj side)) and etch\$3) and (photoresist resist photomask\$3)) and (MEMS wafer substrate workpiece silicon) same oxide with (((first and second) both) adj side) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB |
| 15 | 906 | (((((MEMS wafer substrate workpiece silicon) and oxide with (((first and second) both) adj side)) and etch\$3) and (photoresist resist photomask\$3)) and (MEMS wafer substrate workpiece silicon) same oxide with (((first and second) both) adj side)) and (MEMS wafer substrate workpiece silicon) with oxide with (((first and second) both) adj side) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB |
| 16 | 330 | (((((MEMS wafer substrate workpiece silicon) and oxide with (((first and second) both) adj side)) and etch\$3) and (photoresist resist photomask\$3)) and (MEMS wafer substrate workpiece silicon) same oxide with (((first and second) both) adj side)) and (MEMS wafer substrate workpiece silicon) with oxide with (((first and second) both) adj side)) and (MEMS wafer substrate workpiece silicon) near oxide with (((first and second) both) adj | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB |

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|----|------|--|---|
| 17 | 17 | (((((MEMS wafer substrate workpiece silicon) and oxide with (((first and second) both) adj side)) and etch\$3) and (photoresist resist photomask\$3)) and (MEMS wafer substrate workpiece silicon) same oxide with (((first and second) both) adj side)) and (MEMS wafer substrate workpiece silicon) with oxide with (((first and second) both) adj side)) and (MEMS wafer substrate workpiece silicon) near oxide with (((first and second) both) adj side)) and (MEMS wafer substrate workpiece silicon) near oxide near (((first and second) both) adj side) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB |
| 18 | 18 | SMILE and MEMS | USPAT; US-PGPUB; EPO; JPO; DERWENT; |
| 19 | 9 | ((multilevel multi-level) near etch\$3) and MEMS | USPAT; US-PGPUB; EPO; JPO; DERWENT; |
| 20 | 15 | ("4764244" "4911783" "5006202" "5131978" "5332469" "5542558" "5628917" "5658471" "5683591" "5690841" "5717251" "5770465" "6020272" "6174820" | USPAT |
| 21 | 0 | ((("4764244" "4911783" "5006202" "5131978" "5332469" "5542558" "5628917" "5658471" "5683591" "5690841" "5717251" "5770465" "6020272" "6174820" "6136243").PN.) and locos | USPAT |
| 22 | 1 | ((("4764244" "4911783" "5006202" "5131978" "5332469" "5542558" "5628917" "5658471" "5683591" "5690841" "5717251" "5770465" "6020272" "6174820" "6136243").PN.) and latent | USPAT |
| 23 | 0 | ((("4764244" "4911783" "5006202" "5131978" "5332469" "5542558" "5628917" "5658471" "5683591" "5690841" "5717251" "5770465" "6020272" "6174820" "6136243").PN.) and smile | USPAT |
| 24 | 52 | MEMS and (smile locos latent adj mask\$3) | USPAT |
| 25 | 9 | MEMS and smile | USPAT |
| 26 | 2 | MEMS and delayed adj locos | USPAT |
| 27 | 45 | MEMS and locos | USPAT |
| 28 | 2 | MEMS and latent adj mask\$3 | USPAT |

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|----|------|---|---|
| 1 | 8 | mems and delayed adj locos | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB |
| 2 | 62 | mems and locos | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB |
| 3 | 54 | (mems and locos) not (mems and delayed adj locos) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB |
| 4 | 8 | ((mems and locos) not (mems and delayed adj locos)) and (si3n4 "si.sub.3 N.sub.4" nitride) and thermal\$3 adj oxid\$5 | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB |
| 5 | 2 | ("6464892").PN. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB |
| 6 | 15 | ("4764244" "4911783" "5006202" "5131978" "5332469" "5542558" "5628917" "5658471" "5683591" "5690841" "5717251" "5770465" "6020272" "6174820" | USPAT |
| 7 | 2 | ("6444138").PN. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB |
| 8 | 8 | ("4911783" "5006202" "5131978" "5717251" "5770465" "6020272" "6136243" "6174820").PN. | USPAT |
| 9 | 7 | ((("4764244" "4911783" "5006202" "5131978" "5332469" "5542558" "5628917" "5658471" "5683591" "5690841" "5717251" "5770465" "6020272" "6174820" "6136243").PN.) not ((("4911783" "5006202" "5131978" "5717251" "5770465" "6020272" "6136243" "6174820").PN.) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB |
| 10 | 11 | MEMS and (dope dopant doping) and ((pad adj oxide) with (nitride SiN Si3N4 "si.sub.3 N.sub.4")) and contact | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB |
| 11 | 1310 | (dope dopant doping) and ((pad adj oxide) with (nitride SiN Si3N4 "si.sub.3 N.sub.4")) and contact | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB |
| 12 | 225 | ((dope dopant doping) and ((pad adj oxide) with (nitride SiN Si3N4 "si.sub.3 N.sub.4")) and contact) and deposit\$3 near metal | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB |
| 13 | 1 | ((dope dopant doping) and ((pad adj oxide) with (nitride SiN Si3N4 "si.sub.3 N.sub.4")) and contact) and deposit\$3 near metal) and (dope dopant doping) with "same" near (substrate wafer) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB |
| 14 | 13 | ((dope dopant doping) and ((pad adj oxide) with (nitride SiN Si3N4 "si.sub.3 N.sub.4")) and contact) and (dope dopant doping) with "same" near (substrate wafer) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB |
| 15 | 1452 | (dope dopant doping) and ((pad adj oxide) same (nitride SiN Si3N4 "si.sub.3 N.sub.4")) and contact | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB |
| 16 | 1621 | (dope dopant doping) and ((pad adj oxide) and (nitride SiN Si3N4 "si.sub.3 N.sub.4")) and contact | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB |
| 17 | 15 | MEMS and ((dope dopant doping) and ((pad adj oxide) and (nitride SiN Si3N4 "si.sub.3 N.sub.4")) and contact) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB |
| 18 | 4 | (MEMS and ((dope dopant doping) and ((pad adj oxide) and (nitride SiN Si3N4 "si.sub.3 N.sub.4")) and contact) not (MEMS and (dope dopant doping) and ((pad adj oxide) with (nitride SiN Si3N4 "si.sub.3 N.sub.4")) and contact) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB |
| 19 | 72 | MEMS and LOCOS | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB |
| 20 | 18 | MEMS and SMILE | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB |
| 21 | 1016 | MEMS and LATENT | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB |